

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

For: PROCESS AND INTEGRATION
SCHEME FOR FABRICATING
CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND
SEMICONDUCTOR COMPONENTS
INCLUDING CONDUCTIVE THROUGH-
WAFER VIAS

VIA ELECTRONIC FILING
June 25, 2007

Confirmation No.: 2525

Examiner: W. Lindsay Jr.

Group Art Unit: 2812

Attorney Docket No.: 2269-5859US
(02-0390.00/US)

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES
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Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
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Sir:

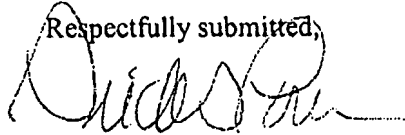
1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.
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Boise, Idaho 83707-0006

Serial No. 10/668,914

2. The Customer Number for the Fee Addressee is **26809**.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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Date: June 25, 2007

BGP/dlm:eg
Document in ProLaw